EXPRESS MAIL NO .: EV349852007 PAGE 1 of 4 1/4 **BIAS ARE APPLIED AND** COIL BIAS AND WAFER APPLY COIL BIAS AND WAFER BIAS POWER FOR DEPOSITION **DEPOSITION STEP DEPOSITION STEP** N (28sccm) IS INTRODUCED  $(Ar/N_2 = 40/28)$ **METALIC TIN** 208 -300 -POWER RAMP STEP POWER RAMP STEP TARGET, RF COIL TARGET AND RF WITH Ar ONLY **PUMP DOWN** POWER ARC **PUMP DOWN** POWER ARC **TURNED ON TURNED ON** (Ar/N=40/30) PUMP DOWN PUMP DOWN DC AND RF 200 -204 -206 GAS STABILIZATION STEP GAS STABILIZATION STEP **INTO THE CHAMBER** NTO THE CHAMBER Ar (40sccm) ALONE ARC INTRODUCED ARE INTRODUCED N (30sccm) GASES Ar (40sccm) and 202 100

AMAT/3177.D1/CPI/L/B/PJS

METHOD AND APPARATUS FOR IONIZED PLASMA DEPOSITION

APPLIED MATERIALS, INC.

WEI WANG, JAMES VAN GOGH

CONF. No.:

UNKNOWN

HEREWITH

ATTY DKT. NO.: U.S. SERIAL NO.:

FILED:

TITLE:

APPLICANT:

INVENTOR:

ATTY DKT. NO.:

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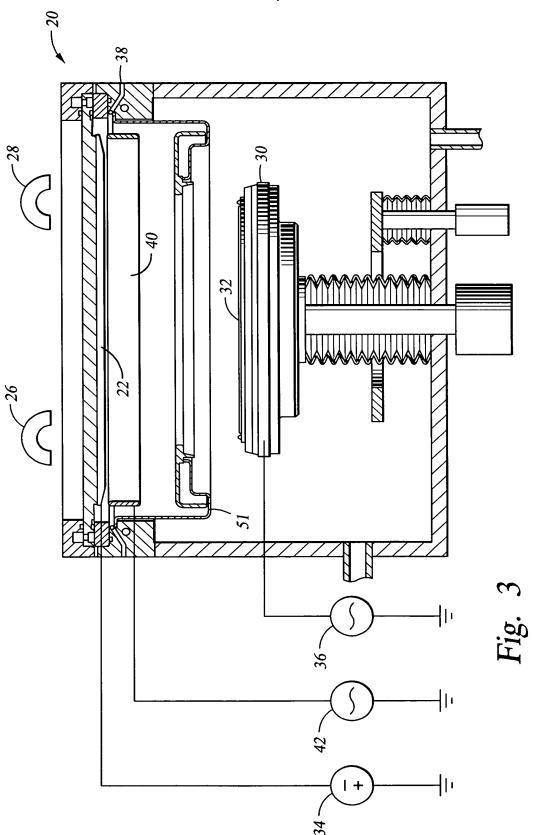
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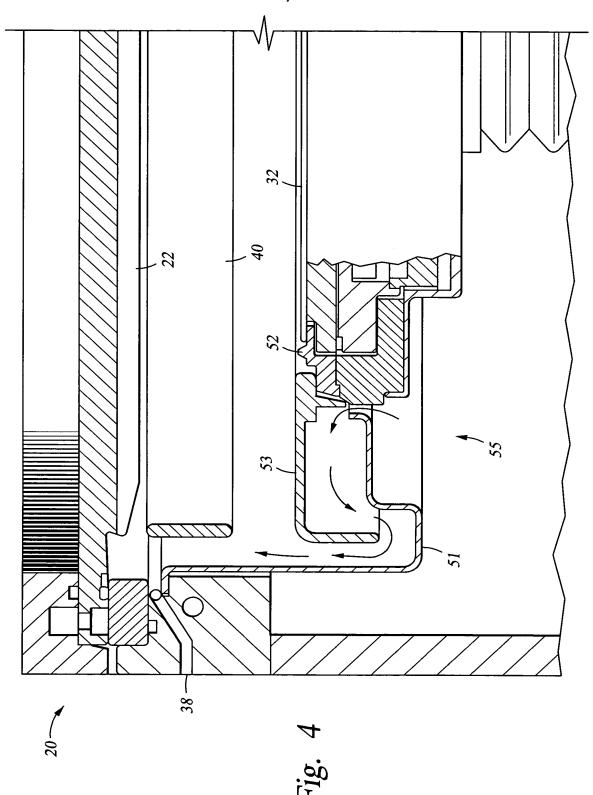
APPLIED MATERIALS, INC. METHOD AND APPARATUS FOR IONIZED PLASMA DEPOSITION

APPLICANT: TITLE: INVENTOR: WEI WANG, JAMES VAN GOGH EXPRESS MAIL NO.: EV349852007

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